

(0,635 mm) .025"

QFS SERIES

RUGGED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QFS

Insulator Material:

Liquid Crystal Polymer

Contact & Ground Plane Material:

Phosphor Bronze

Plating:

Au over 50µ" (1,27 µm) Ni
(Tin on Ground Plane Tail)

Current Rating:

Contact:

2.6 A per pin

(1 pin powered per row)

Ground Plane:

15.7 A per ground plane

(1 ground plane powered)

Voltage Rating:

300 VAC mated with QMS

Operating Temp:

-55°C to +125°C

RoHS Compliant: Yes

Processing:

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (026-078)

Board Stacking:

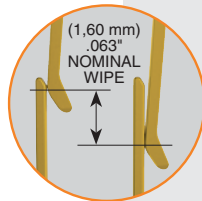
For applications requiring more than two connectors per board contact ipg@samtec.com

Board Mates:

QMS

Cable Mates:

6QCD



Increased insertion depth for rugged applications

Integral metal plane for power or ground

ALSO AVAILABLE
(MOQ Required)

- Other platings
 - Without PCB Alignment Pins
 - Hot Pluggable
 - 4 banks (104 -SE, 64 -DP)
- Contact Samtec.

QMS/QFS 10 mm Stack Height	Type	Rated @ 3dB Insertion Loss	
		with PCB effects*	w/o PCB effects**
Single-Ended Signaling	-D	9 GHz / 18 Gbps	8 GHz / 16 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps	8.5 GHz / 17 Gbps
Differential Pair Signaling	-DP	7.5 GHz / 15 Gbps	9 GHz / 18 Gbps

*Performance data includes effects of a non-optimized PCB.
**Test board losses de-embedded from performance data.

Performance data for other stack heights and complete test data available at www.samtec.com?QFS or contact sig@samtec.com

Final Inch® | 28+
C E R T I F I E D | G b p s

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

QFS — **PINS PER ROW NO. OF PAIRS** — **LEAD STYLE** — **PLATING OPTION** — **TYPE** — **A** — **OTHER OPTION**

-026, -052, -078
(52 total pins per bank = -D)

-016, -032, -048
(16 pairs per bank = -D-DP)

Specify
LEAD
STYLE
from
chart

-L
(-04.25 lead style only)
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane
(Tin on Signal Pin tails, and Ground Plane tails)

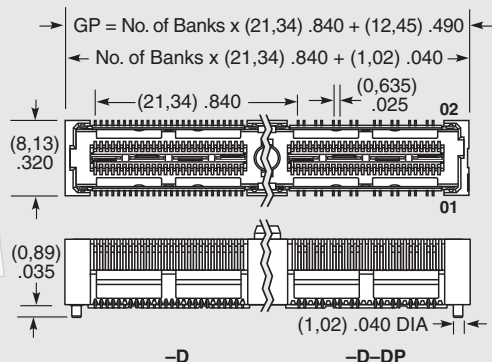
-SL
(-06.25 lead style only)
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane
(Tin on Signal Pin tails, and Ground Plane tails)

-D
= Single-Ended
-D-DP
= Differential Pair
(-04.25 lead style only)

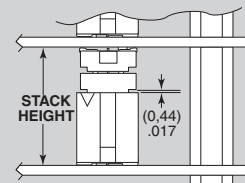
-GP
= Guide Holes
(-04.25 lead style only)

MATED HEIGHT*				
LEAD STYLE	A	QMS LEAD STYLE		
		-05.75	-06.75	-09.75
-04.25 (7,44) .293	10 mm	11 mm	14 mm	
-06.25 (9,42) .371	12 mm	13 mm	16 mm	

*Processing conditions will affect mated height.

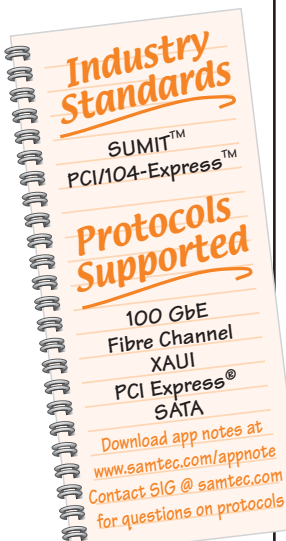


APPLICATION



Requires Standoff
SO-1524-03-01-01-L for 15,24 mm
or SO-2215-02-01-01-L for 22 mm
board spacing. Connectors designed to not fully seat when mated.

INDUSTRY STANDARD	INTERCONNECTS			
	TERMINAL	SOCKET	BANKS	STACK HEIGHT
SUMIT™	ASP-129637-01	ASP-129646-01	1	15,24 mm
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15,24 mm
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm



Note: Some lengths, styles and options are non-standard, non-returnable.